

SIITME 2023



CALL FOR EXHIBITORS OCTOBER 18-21, 2023

IEEE 29th International Symposium for Design and Technology in Electronic Packaging

Craiova, Romania

SIITME (International Symposium for Design and Technology in Electronic Packaging) was initiated in 1995 and takes place annually in a different location in Romania.

The event is a bridge between the electronics industry and academia in our region. SIITME is strongly oriented to promote young electronics engineers in a culture of innovation and to represent a fertile environment for scientific and technical discussions.

The SIITME conference is a powerful and reliable forum where electronics industry specialists come into direct contact with researchers and academics, for the benefit of both parties and with a significant impact on technological development and innovation.

SIITME is one of the international scientific conferences with electronic packaging as its main objective. By promoting collaboration between the electronics industry, taken in a broad sense (hardware, software, communications, information processing), and the corresponding research environment, SIITME ensures both a prosperous environment for young researchers and students to get feedback on their work from their more senior counterparts as well as a thriving community in which beneficial partnerships can be created between academic researchers and industry professionals.

AUDIENCE

The focus of the conference on the issue of intelligent systems provides the necessary premises to stimulate the interest of the research environment for access to solutions in accordance with the current trend imposed by IoT, IoE.

The SIITME conference stands out from other conferences in that it stimulates the training of young human resources in accordance with the requirements of product innovation with high added value. In addition to the young participating teaching staff, PhD students, master's students and even final year undergraduate students are encouraged to participate in SIITME. The promotion of educational methods connected to the requirements of the European Pact for Skills program.

It has become a well-known IEEE conference, having the technical sponsorship of the IEEE-EPS Hu&Ro Joint Chapter and the IMAPS Romania Chapter. The conference proceedings are included in the IEEE eXplore database, being indexed by ISI (Clarivate).

To meet the audience interest best, the exhibitors should focus on the following topics:

- Emerging topics in electronic packaging
- New components and manufacturing technologies
- Printable Electronics, Smart Textiles and Healthcare
- Sensors, actuators and microsystems
- Nanomaterials, nanoelectronics and nanotechnology
- Embedded Systems, Robotics and Artificial Intelligence
- Power electronics and thermal management
- Smart grid and renewable energy
- Virtual prototyping and system validation
- Quality management, applied reliability, characterization and diagnosis of test failures
- Corrosion in electronics
- Digitalization Challenges and Global Electronics Education

VENUE

The event will take place at the University of Craiova, the Main Lobby being offered as expositional space both for Poster Presentations as well as the Industrial Exhibitions. This space will be heavily transitioned by all participants at the conference and therefore offers prime real estate for companies wanting to promote their products, goods and/or services.



EXHIBITION SCHEDULE

The conference will be a four-day-event, where the first half day will be dedicated to Technical Short Courses / Professional Development Courses (PDCs), and the second half to invited keynotes and parallel technical sessions. The second and third days will be fully dedicated to technical sessions, special sessions, and further keynotes. The final day includes a farewell breakfast and coffee. The exhibition schedule will span three days, as follows:

Wednesday, October 18th

10:00 – 12:00 Setup

14:00 – 18:00 Exhibition

Thursday, October 19th

09:00 – 17:00 Exhibition

Friday, October 20th

08:00 – 17:00 Exhibition

17:00 – 19:00 Dismantling

EXHIBITION STANDS

Standard Exhibition Stand – 700 EUR

- Standard 2m x 2m booth equipped with table and chair
- Company logo printed and displayed on top of the booth
- 2 m space for your company branded backwall and/or roll-ups (self-delivered)
- Power supply 220 V distribution board for standard usage (laptop, lighting, charger)
- 1 complementary conference pass for company representative
- 10-15-minute company presentation during the industrial session

Available upgrades

- Additional company representative: + 300 EUR
- Extended booth (2m x 4m): + 300 EUR

BOOKING YOUR STAND

In order to book your stand, or if you have any questions regarding the SIITME 2023 expo, contact:

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